

Industry-Academic Forum on EMC 2023

Hardware Development at IBM Germany

Overview

This series of talks – intended primarily for students and Ph.D. students interested in advanced SI/PI – introduces the IBM Z mainframe and its hardware. The focus will be on the development of the chip and the electronic packaging, with a special emphasis on signal and power integrity. The final talk will be a brief introduction to quantum computing at IBM.

Program (Friday, February 3)

2:00-2:20 Introduction: IBM Z and Telum Chip

2:20-2:40 Overview of Chip Development

2:40-3:00 Break + Q&A

3:00-3:15 Introduction to Packaging

3:15-3:35 Power Integrity

3:35-4:00 Signal Integrity

4:00-4:20 Break + Q&A

4:20-4:40 Quantum

4:40-5:00 Open Discussion



(Image: IBM. With permission)

Presenters

Dr. Xiaomin Duan, Dr. Katharina Scharff

Hardware Packaging Development IBM Systems

IBM Deutschland Research & Development, Schönaicher Str. 220, 71032 Böblingen

Registration

The event is part of the EMC Forum 2023 at TUHH. Prior registration is required at:

<https://www.emcforum.eu/contact/>

Venue

Hamburg University of Technology (TUHH), Building B, Room B 0.001

Further Information

Please see website of the EMC Forum at <https://www.emcforum.eu/>